

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L4	183	"29"/\$.ccls. and (over adj mold) or mold and PCB and backplate and therma\$5 near contact and shroud and electronic and (environment\$5 or sealingly) and (pressure or force)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/10 15:19
L5	0	"29"/\$.ccls. and ((over adj mold) or mold) and PCB and backplate and therma\$5 near contact and shroud and electronic and (environment\$5 or sealingly) and (pressure or force)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/10 15:21
L6	0	"29"/\$.ccls. and ((overmold) or mold) and PCB and backplate and therma\$5 near contact and shroud and electronic and (environment\$5 or sealingly) and (pressure or force)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/10 15:24
L7	0	((overmold) or mold) and PCB and backplate and therma\$5 near contact and shroud and electronic and (environment\$5 or sealingly) and (pressure or force)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/10 15:21
L8	0	((overmold) or mold) and PCB and backplate and therma\$5 near contact and shroud and electronic and (environment\$5 or sealingly) and (pressure or force)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/10 15:22
L9	0	((overmold) or mold) and PCB and backplate and therma\$5 near contact and shroud and electronic and (environment\$5 or sealingly)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/10 15:22
L10	0	((overmold) or mold) and PCB and backplate and therma\$5 near contact and shroud and electronic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/10 15:22
L11	0	(overmold or mold) and PCB and backplate and therma\$5 near contact and shroud and electronic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/10 15:23

L12	0	(overmold or mold or over adj mold) and PCB and backplate and therma\$5 near contact and shroud and electronic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/10 15:23
L13	1	"29"/\$.ccls. and (overmold\$5 or over adj molding) with (electronic adj assembly)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/10 15:32
L14	10	("4947235" "5148350" "5570272" "5872332" "6003586" "6180045" "6285551" "6304450" "6432742" "6549426").PN. OR ("6807731").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/02/10 15:27
L15	4	"361"/\$.ccls. and (overmold\$5 or over adj molding) with (electronic adj assembly)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/10 15:32
L18	1026	(439/79).CCLS.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/02/10 17:08
L19	103	L18 and mold	US-PGPUB; USPAT	OR	ON	2005/02/10 17:08
L20	104	L18 and (mold or overmold)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/02/10 17:08
L21	183	L18 and (heat or thermal)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/02/10 17:09
S42	10	("5028988" "5142443" "5268812" "5349823" "5365749" "5463872" "5504924" "5918469").PN. OR ("6122926").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/02/10 11:46
S43	33	("3309577" "4479198" "4581495" "4591949" "4728160" "4748540" "4934764" "4937771" "4937806" "5107400" "5132876" "5224019").PN. OR ("5426564").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/02/10 11:49
S44	9	("5244416" "5348488" "5699235" "5712765" "5920463" "6045397" "6171133").PN. OR ("6572412").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/02/10 12:12

S45	10	("4875863" "5186633" "5240422" "5468154" "5980314" "6033258").PN. OR ("6171133"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/02/10 13:21
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